

AMENDMENT AND RESPONSE UNDER 37 C.F.R. § 1.121

U.S. Patent Application Serial No.: 10/538,856

Attorney Docket No.: 026390-00028

AMENDMENTS TO THE CLAIMS

Listing of the claims:

Following is a listing of all claims in the present application, which listing supersedes all previously presented claims:

1. (Currently Amended) A component for a in a film forming equipment for forming a thin film on a substrate, the component having a matrix material and being characterized by that a metal a first film layer electrochemically less noble than the matrix metal material of said component is formed on the surface of the matrix metal material through thermal spraying, vapor depositing, sputtering, laminating or other process.
2. (Currently Amended) The component as claimed in of claim 1, characterized by that further having a second metal film layer electrochemically more noble than said matrix metal material [[is]] formed on the surface of said metal first film layer through thermal spraying, vapor depositing, sputtering, laminating or other process.
3. (Withdrawn) A method of cleaning a component for a film forming equipment, characterized by that after a thin film has been formed on the substrate by the film forming equipment, the component as claimed in claim 1 or 2 is dipped in a cleaning fluid to remove an deposited film consisting of the film forming material from the component.
4. (Withdrawn) The method as claimed in claim 3, characterized by that a positive electric field is applied to the matrix metal material of said component dipped in the cleaning fluid.